

REPORT DOCUMENTATION PAGE

Form Approved
OMB NO. 0704-0188

Public Reporting burden for this collection of information is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comment regarding this burden estimates or any other aspect of this collection of information, including suggestions for reducing this burden, to Washington Headquarters Services, Directorate for Information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302, and to the Office of Management and Budget, Paperwork Reduction Project (0704-0188), Washington, DC 20503.

1. AGENCY USE ONLY (Leave Blank)		2. REPORT DATE 23 September 2000	3. REPORT TYPE AND DATES COVERED Final Report
4. TITLE AND SUBTITLE Kinetic-Energy-Enhanced Neutral Etching		5. FUNDING NUMBERS <i>DAAG55-97-1-0396</i>	
6. AUTHOR(S) Stephen R. Leone			
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) JILA, University of Colorado Boulder, CO 80309-0440		8. PERFORMING ORGANIZATION REPORT NUMBER FINAL REPORT - 01	
9. SPONSORING / MONITORING AGENCY NAME(S) AND ADDRESS(ES) U. S. Army Research Office P.O. Box 12211 Research Triangle Park, NC 27709-2211		10. SPONSORING / MONITORING AGENCY REPORT NUMBER <i>ARO 37401.2-PH</i>	
11. SUPPLEMENTARY NOTES The views, opinions and/or findings contained in this report are those of the author(s) and should not be construed as an official Department of the Army position, policy or decision, unless so designated by other documentation.			
12 a. DISTRIBUTION / AVAILABILITY STATEMENT Approved for public release; distribution unlimited.		12 b. DISTRIBUTION CODE	
13. ABSTRACT (Maximum 200 words) The goal of this project is to develop an understanding of kinetic-energy-enhanced effects in the processing/etching steps of semiconductor fabrication. An instrument was developed that uses a kinetic-energy-variable argon ion source together with independent dosing of neutral reactive molecules to probe the evolution of neutral and ionic products during etching. These products are probed by laser ionization. Studies determined the effects of ion beam energy on the yields of neutral and ionic silicon and silicon chloride products during the etching of silicon by chlorine. The temperature dependence of the neutral and ion products was measured.			
14. SUBJECT TERMS Silicon, Etching, Ion Beam, Product Threshold		15. NUMBER OF PAGES 5	
		16. PRICE CODE	
17. SECURITY CLASSIFICATION OR REPORT UNCLASSIFIED	18. SECURITY CLASSIFICATION ON THIS PAGE UNCLASSIFIED	19. SECURITY CLASSIFICATION OF ABSTRACT UNCLASSIFIED	20. LIMITATION OF ABSTRACT UL

NSN 7540-01-280-5500

Standard Form 298 (Rev.2-89)

Prescribed by ANSI Std. Z39-18

298-102

DIGITAL QUALITY IMPROVED 4

Final Technical Report

Army Research Office Grant No. DAAG55-97-0396 (37401-PH)

"Kinetic-Energy-Enhanced Neutral Etching."

1 September 1997 - 31 August 2000

Principal Investigator: Stephen R. Leone
JILA
University of Colorado
Boulder, CO 80309-0440
(303) 492-5128
email: srl@jila.colorado.edu

Program Manager: David Skatrud
Physics Division
U.S. Army Research Office
P. O. Box 12211
Research Triangle Park, NC 17709-2211

Statement of Problem Studied

The etching of silicon wafers is a ubiquitous process in semiconductor device fabrication. There have been many studies of the species formed during etching, but various aspects of the mechanisms are not completely understood. This program addressed several microscopic mechanisms of silicon etching induced by the interactions of energetic particles (e.g. argon ions) with a silicon surface under conditions of chemical dosing (e.g. molecular chlorine or fluorine). Two laser methods were developed to probe the neutral products of the etching in the presence of large fluxes of ions: laser single photon ionization at 118 nm (9th harmonic of the Nd:YAG laser) and resonantly enhanced, tunable dye laser multiphoton ionization. These techniques revealed a number of important results about the products of the etching process under realistic etching conditions.

Brief Outline of Research Findings

A new method to detect many of the neutral species produced under realistic etching conditions was developed using a method of laser flux monitoring. The method involves a pulsed vacuum ultraviolet laser source (118 nm, 9th harmonic of a Nd:YAG laser) that can ionize the neutral species during the etching process. A silicon wafer is dosed with chlorine molecules and simultaneously bombarded with an energy-variable flux of argon ions. A pulse sequence is used, so that the large fluxes of interfering ionic species are first swept from the zone in front of the wafer. Then the neutral products that were formed as a result of the ion bombardment and chemical etching process are directly interrogated with the laser and a time-of-flight mass spectrometer.

This technique of laser single photon ionization time-of-flight mass spectrometry was used to measure the neutral Si, SiCl, and SiCl₂ etch products during ion-enhanced etching of Si(100) for an ion kinetic energy range of 275-975 eV. The etch products were examined as a function of ion energy, ion flux, and molecular chlorine flux. Direct detection of a significant evolution of silicon neutral atoms was observed, resulting from the simultaneous action of the ion beam and the chlorine chemical reactivity. However, the SiCl product has the greatest yield by far. The yield of each product increases with increasing ion energy. However, the yield ratio of neutral SiCl/Si decreases with increasing ion energy,

suggesting a decrease in the chlorine coverage at higher ion beam energies. The results of this investigation were successfully fit to a simple kinetic model, which incorporates the chlorine coverage under realistic etching conditions and the increase in desorption of silicon with chlorine coverage.

Under argon-ion-enhanced etching conditions of Si(100) by chlorine, the single photon laser ionization method was used to compare the yields of neutral etch products to the yields of ionic etch products, with the latter being measured directly by the time-of-flight mass spectrometer. There is a good correspondence between the ion and neutral products over a wide range of conditions, suggesting that most of the products are formed during the direct impact of the argon ions, rather than due to subsequent thermal chemistry and desorption after the argon ion impact. However, neutral SiCl_2 is observed as an etch product, whereas no yield of ionic SiCl_2^+ is detected at all. The latter result suggests that some neutral products may be formed by subsequent thermal reactions following the ion impact, whereas the ion products are only formed in the direct ion impact event.

The temperature dependence of the ionic and neutral yields of etch products was studied for Si(100) + chlorine with argon-ion-enhanced bombardment. The initial decrease of both the ionic and neutral products with increasing temperature suggests a decreasing chlorine coverage with temperature. However, a substantial increase in the observed ionic product yield at higher temperatures, with a secondary maximum at 800 K, suggests a very different mechanism for the formation of the ion products compared to neutral etch products. The enhanced yield of ion etch products Si^+ and SiCl^+ may be due to electronic properties (e.g. the availability of conduction electrons that change with temperature) in the silicon substrate when heated. The potential use of the ionic products as a means to monitor the predominant neutral etch products versus temperature is specifically ruled out.

Resonantly enhanced multiphoton ionization (REMPI) was also developed as a method to detect Si and SiCl . In addition to greater signal-to-noise achieved with the REMPI method, state-resolved detection was also successful. Initial experiments investigated the spin-orbit excited state populations of Si atoms during thermal and ion-enhanced etching. The results of such studies have the potential to reveal the

local heating by the argon ion impact, however in these studies the spin-orbit states were found to be essentially in thermal or statistical distributions, even during ion-enhanced etching.

Summary of Most Important Findings:

The most important findings are as follows: (1) measurements of the neutral and ionic product yields were obtained during thermal and ion-enhanced etching by use of single photon laser ionization time-of-flight mass spectrometry; (2) Under realistic ion-enhanced etching conditions for Si(100) by chlorine, we showed that neutral silicon atoms are released directly (in agreement with theory), but that SiCl is the most dominant product, in contrast to earlier investigations; (3) studies were performed on the temperature dependencies of the ionic and neutral products during etching; (4) resonant-enhanced multiphoton ionization was developed and used to detect the spin-orbit state distributions of atomic products during etching.

ARO Publications on Etching (1997-present):

N. Materer, R. S. Goodman, and S. R. Leone, "Laser single-photon ionization mass spectrometry measurements of SiCl and SiCl₂ during thermal etching of Si(100)," J. Vac. Sci. Tech. A **15**, 2134 (1997).

R. S. Goodman, N. Materer, and S. R. Leone, "Ar, N₂ and Cl₂ electron cyclotron resonance plasmas measured by time-of-flight analysis: Neutral kinetic energies and source gas cracking," J. Vac. Sci Technol. B **15**, 971 (1997).

N. Materer, R. S. Goodman, and S. R. Leone, "Comparison of electron cyclotron resonance and radio-frequency inductively coupled plasmas of Ar and N₂: Neutral kinetic energies and source gas cracking," J. Appl. Phys. **83**, 1917 (1998).

R. S. Goodman, N. Materer, and S. R. Leone, "Ion-enhanced etching of Si(100) with molecular chlorine: Reaction mechanisms and product yields," J. Vac. Sci. Technol. A, **17**, 3340 (1999).

N. Materer, R. S. Goodman, and S. R. Leone, "Temperature dependence of neutral and positively charged Si and SiCl etch products during argon-ion enhanced etching of Si(100) by Cl₂," J. Vac. Sci. Technol. B, **18**, 191 (2000).

N. Materer, Rory S. Goodman, and Stephen R. Leone, "Ion-enhanced Etching of Si(100) with Molecular Chlorine: Neutral and Ionic Product Yields as a Function of Ion Kinetic Energy," J. Phys. Chem. B **104**, 3261 (2000).

T. A. Barckholtz, L. A. McDonough, and S. R. Leone, "Spin-orbit distributions of Si atoms produced during the Ar⁺-enhanced etching of a Si(100) surface," in preparation.

Participants and Degrees Awarded

Rory Goodman, Ph.D. University of Colorado, 1999. Presently Scientific Staff at Seagate

Nick Materer, Postdoctoral Associate, presently Assistant Professor of Chemistry, Oklahoma State University

Laurie McDonough, CU Graduate Student, Ph.D. degree in progress

Timothy Barckholtz, Postdoctoral Associate, seeking academic faculty positions, fall 2000.

Stephen Leone, Principal Investigator.

Reportable Inventions:

none